

<b>Notice of References Cited</b>	Application/Control No. 10/820,312	Applicant(s)/Patent Under Reexamination OKA ET AL.	
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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

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	W	Wikipedia; <a href="http://en.wikipedia.org/wiki/Thin-film_deposition">http://en.wikipedia.org/wiki/Thin-film_deposition</a>
	X	Society of Vacuum Coaters; 44th anual technical conference proceedings; 2001; society of vacuum coaters.

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